

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0017] in the specification with the following amended paragraph.

[0017] In yet another embodiment, the CMP wetting composition of the present invention can be used in a CMP apparatus 200, a top view of which is illustrated schematically in FIG. 2. Apparatus 200 may comprise a plurality of load cups 202, 204, 206. ~~The CMP apparatus 200 is further detailed and described in U.S. Appn. No. _____, which is incorporated herein by reference.~~ Generally, the CMP apparatus 200 also includes a plurality of chemical mechanical planarization carrier heads 208, 210, 212 positioned about a centrally located robot 214. The robot 214 is configured to receive a wafer 220 (shown in phantom) and transport it, for example, from a cache 222 to one of the load cups 202-206. Each of the CMP carrier heads 208-212 is positioned over a polishing pad (not illustrated) that is configured to utilize a CMP slurry to polish the wafer 220 in a manner well known to those of skill in the CMP art. Each load cup 202-206 is coupled to a load cup arm 224, 226, 228 that is configured to pivot between an off-load position (as illustrated) to a load position that is located beneath a corresponding carrier head 208-212. Although three carrier heads are illustrated, CMP apparatus 200 can be configured with any number of carrier heads and with a proportionate number of load cups and associated elements.